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		(multiple or plural or different or several)		0000/07/00 40 04
5	35	((716/\$.ccls. and (jtag or tap or (boundary adj3 scan))) not	USPAT	2002/07/03 10:31
		(716/4.ccls. and (jtag or tap or (boundary adj3 scan)))) and		
		((multiple or plural or different or several) with device)		
6	5	jtag and ((select\$3 with (id or identification)) with code)	USPAT	2002/07/03 11:02
-	998	jtag	USPAT	2002/05/01 15:04
-	502	jtag and id\$2	USPAT	2002/07/02 12:45
-	133	itag and id\$2 and (reconfigur\$7 or confirgur\$7)	USPAT	2002/05/01 15:06
_	123	jtag and id\$2 and (reconfigur\$7 or confirgur\$7) and software	USPAT	2002/05/01 15:06
_	88	jtag and (device with id\$2) and (reconfigur\$7 or confirgur\$7)	USPAT	2002/05/01 15:06
		and software		
_	72190	boundary adj2 scan or test adj access adj port or tap	USPAT	2002/07/02 12:47
_	1870	(boundary adj2 scan or test adj access adj port or tap) same	USPAT	2002/07/02 12:48
		(id or identification or code)		
_	1991	(boundary adj2 scan or test adj access adj port or tap) same	USPAT	2002/07/02 12:48
-		(id or identification or code)		
\ _	253	((boundary adj2 scan or test adj access adj port or tap) same	USPAT	2002/07/02 12:48
	200	(id or identification or code)) same voltage		
	9	(((boundary adj2 scan or test adj access adj port or tap)	USPAT	2002/07/02 15:25
		same (id or identification or code)) same voltage) same pin\$2		
	1	(tap with ((multiple or plural) with device with id))	USPAT	2002/07/02 15:27
_	2	(tap same ((multiple or plural) with device with id))	USPAT	2002/07/02 15:28
] -	2	((tap or jtag or (boundary adj3 scan)) same ((multiple or	USPAT	2002/07/02 15:29
1-		plural) with device with id))		
	215	(plural or multiple) with id with code	USPAT	2002/07/02 15:30
_	11	((plural or multiple) with id with code) and (jtag or tap)	USPAT	2002/07/02 15:31
-	446	716/4.ccls.	USPAT	2002/07/02 15:31
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3 A register-controlled symmetrical DLL for double-data-rate DRAM Feng Lin; Miller, J.; Schoenfeld, A.; Ma, M.; Baker, R.J. Solid-State Circuits, IEEE Journal of , Volume: 34 Issue: 4 , April 1999 Page(s): 565 -568

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4 Two types of sound tool f r editing speech signal: sound cutter and sound edit r

Sagisaka, T.; Munakata, T.

Multimedia Computing and Systems, 1999. IEEE International Conference on , 2,1999

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